

**IN THE CLAIMS:****Amendments to the Claims**

Please amend claims 39 and 41 and add the following new claims as shown below.

**Listing of Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 1-14 (canceled)

15. (withdrawn) A method of fabricating an edge emitting/incidence type semiconductor light receiving element formed by sequentially laminating on a substrate a plurality of different thin film layers including a light absorbing layer, wherein a thin film growth at a predetermined region of at least said light absorbing layer is prohibited during steps of laminating said light absorbing layer and subsequent thin film layers so that said semiconductor light receiving element may be adapted to be positioned in place.

16. (withdrawn) A method of fabricating an edge emitting/incidence type semiconductor light receiving element formed by sequentially laminating on a substrate a plurality of different thin film layers including a light absorbing layer, comprising an etching step for eliminating a portion of said light absorbing layer existing at a predetermined region of said light absorbing layer so that said semiconductor light receiving element may be adapted to be positioned in place.

## Claims 17-38 (canceled)

39. (currently amended) A light transmitting module comprising:  
a substrate;  
an optical fiber disposed on one surface of said substrate; and  
an edge emitting/incidence type light receiving element ~~HAVING~~ having a  
layer disposed on said one surface of said substrate;  
wherein said layer of said edge emitting/incidence type light receiving element  
includes a light absorbing portion and another portion which is a non-light absorbing  
portion and which defines a space region of said layer, said non-light absorbing  
portion being of a size sufficient to enable a predetermined mounting accuracy with a  
predetermined measuring accuracy achievable when said substrate is measured  
with a camera.

40. (previously presented) A light transmitting module according to claim  
39, wherein said light absorbing portion of said layer at least partially surrounds said  
another portion of said layer which is said non-light absorbing portion and which  
defines said space region of said layer.

41. (currently amended) A light transmitting module according to claim 39,  
wherein said edge emitting/incidence type light receiving element is positioned on  
said one surface of said substrate by projecting a light having a wavelength which is  
absorbed by said light absorbing portion of said layer and which is enabled to pass  
said another portion of said layer which is said non-light absorbing portion which  
~~defines said space region is enabled to pass.~~

42. (previously presented) A light transmitting module according to claim 39, wherein said edge emitting/incidence type light receiving element is a semiconductor light receiving element.

43. (previously presented) A light transmitting module according to claim 42, wherein said optical fiber is optically coupled to said semiconductor light receiving element.

44. (previously presented) A light transmitting module according to claim 42, further comprising a semiconductor laser mounted on said substrate, said semiconductor light receiving element being optically coupled to at least one of said semiconductor laser and said optical fiber.

45. (previously presented) A light transmitting module according to claim 43, wherein said semiconductor light receiving element disposed on said substrate is configured by being packaged with either ceramic or resin.

46. (previously presented) A light transmitting module according to claim 44, wherein said semiconductor light receiving element disposed on said substrate is configured by being packaged with either ceramic or resin.

47. (new) A light transmitting module according to claim 39, wherein at least a part of said light absorbing portion and at least a part of said non-light absorbing portion lie in substantially a same plane.

48. (new) A light transmitting module comprising:  
a substrate;

an optical fiber disposed on one surface of said substrate;  
an edge emitting/incidence type light receiving element having a layer disposed on said one surface of said substrate; and  
a marker disposed on said one surface of said substrate;  
wherein said layer of said edge emitting/incidence type light receiving element includes a light absorbing portion and another portion which is a non-light absorbing portion and which defines a space region of said layer, said non-light absorbing portion enabling observation of said marker therethrough.

49. (new) A light transmitting module according to claim 48, wherein said light absorbing portion of said layer at least partially surrounds said another portion of said layer which is said non-light absorbing portion and which defines said space region of said layer.

50. (new) A light transmitting module according to claim 48, wherein said edge emitting/incidence type light receiving element is positioned on said one surface of said substrate by projecting a light having a wavelength which is absorbed by said light absorbing portion of said layer and which is enabled to pass said another portion of said layer which is said non-light absorbing portion .

51. (new) A light transmitting module according to claim 48, wherein said edge emitting/incidence type light receiving element is a semiconductor light receiving element.

52. (new) A light transmitting module according to claim 51, wherein said optical fiber is optically coupled to said semiconductor light receiving element.

53. (new) A light transmitting module according to claim 51, further comprising a semiconductor laser mounted on said substrate, said semiconductor light receiving element being optically coupled to at least one of said semiconductor laser and said optical fiber.

54. (new) A light transmitting module according to claim 52, wherein said semiconductor light receiving element disposed on said substrate is configured by being packaged with either ceramic or resin.

55. new A light transmitting module according to claim 53, wherein said semiconductor light receiving element disposed on said substrate is configured by being packaged with either ceramic or resin.

56. (new) A light transmitting module according to claim 48, wherein at least a part of said light absorbing portion and at least a part of said non-light absorbing portion lie in substantially a same plane.

57. (new) A method of fabricating a light-transmitting module comprising the steps of:

moving a light receiving element having a light absorbing portion and a non-light absorbing portion to a position above a substrate having a marker;

picking up an image of said substrate from said non-light absorbing portion with a camera;

determining a mounting position of said light receiving element based on whether said marker is present in the picked-up image; and

mounting said light receiving element at said mounting position.